

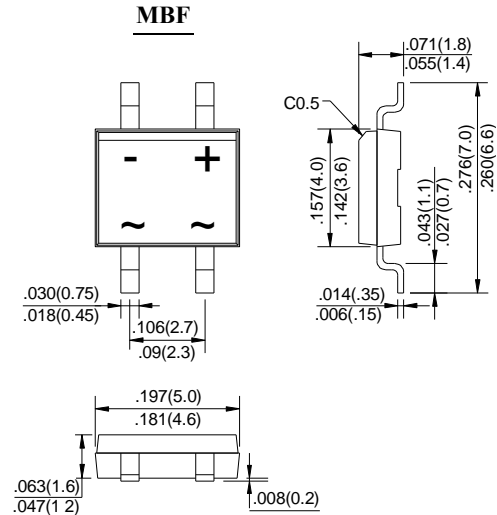
**VOLTAGE RANGE: 50 - 1000V**  
**CURRENT: 0.5 A**

### Features

- Glass passivated chip junctions
- Plastic material has U/L flammability classification 94V-0
- High surge overload rating: 25A peak
- Saves space on printed circuit boards
- High temperature soldering guaranteed: 260°C/10 seconds at 5 lbs2(0kg) tension

### Mechanical Data

- Case: Molded plastic body over passivated junctions
- Terminals: Plated leads solderable per MIL-STD-750, Method 2026
- Polarity: Polarity symbols marked on body
- Dimensions in inches and (millimeters)
- Mounting Position: Any
- Weight: 0.0078 ounce, 0.22 gram



Dimensions in inches and (millimeters)

### Maximum Ratings and Electrical Characteristics T<sub>A</sub> = 25°C unless otherwise specified

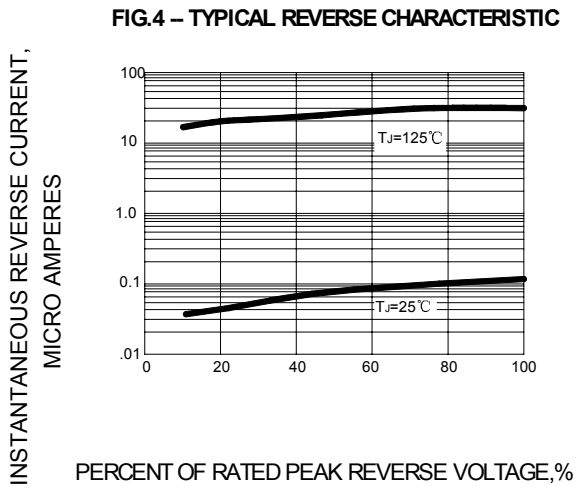
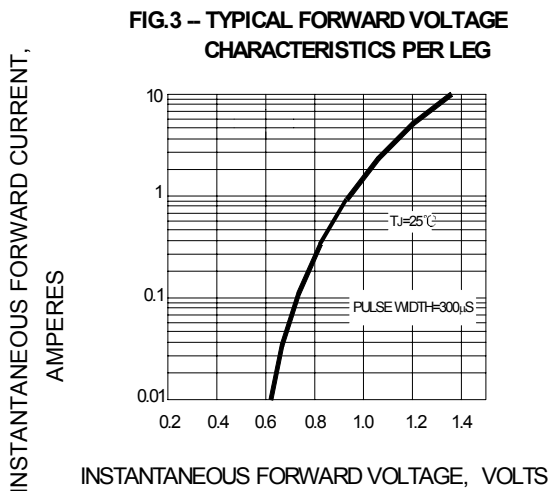
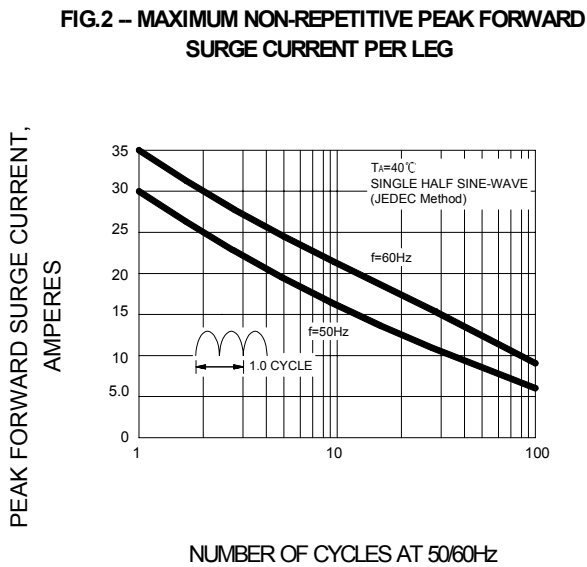
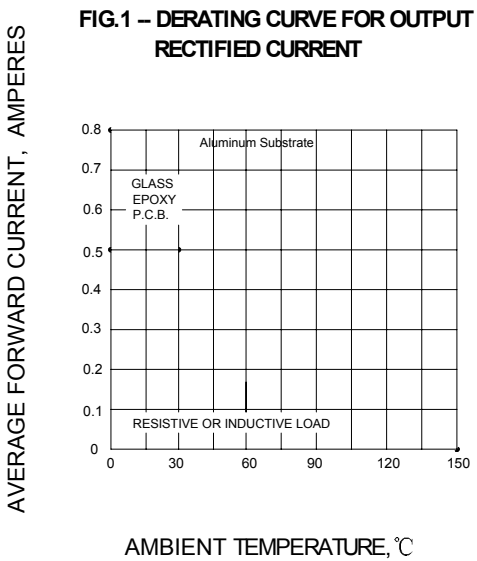
Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	MB05F	MB1F	MB2F	MB4F	MB6F	MB8F	MB10F	Unit
Maximum recurrent peak reverse voltage	V <sub>RRM</sub>	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V <sub>DC</sub>	50	100	200	400	600	800	1000	V
Maximum average forward output current @T <sub>A</sub> =25°C	I <sub>F(AV)</sub>	0.5							A
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load	I <sub>FSM</sub>	25							A
Maximum instantaneous forward voltage @ 0.4 A	V <sub>F</sub>	1.0							V
Maximum reverse current @T <sub>A</sub> =25°C at rated DC blocking voltage @T <sub>A</sub> =100°C	I <sub>R</sub>	5.0 0.5							μA mA
Typical junction capacitance per leg (NOTE 3)	C <sub>J</sub>	13							pF
Typical thermal resistance per leg (NOTE 1) (NOTE 2)	R <sub>JA</sub> R <sub>JL</sub>	85 20							°C/W
Operating junction temperature range	T <sub>J</sub>	- 55 ---- + 150							°C
Storage temperature range	T <sub>STG</sub>	- 55 ---- + 150							°C

NOTES: (1) On glass epoxy P.C.B. mounted on 0.05 x 0.05" (1.3 x 1.3mm) pads

(2) On aluminum substrate P.C.B. with an area of 0.8" x 0.8" (20 x 20mm) mounted on 0.05 x 0.05" (1.3 x 1.3mm) solder pad

(3) Measured at 1.0 MHz and applied reverse voltage of 4.0 Volts



**FIG.5 – TYPICAL JUNCTION CAPACITANCE PER ELEMENT**

